

# **ZXTP25020DZ 20V PNP high gain transistor in SOT89**

## **Summary**

 $BV_{CEO} > -20V$ 

 $BV_{ECO} > -4V$ 

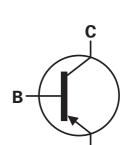
 $I_{C(cont)} = 5A$ 

 $V_{CE(sat)} < -65 \text{mV} @ -1 \text{A}$ 

 $R_{CE(sat)} = 39m\Omega$ 

 $P_D = 2.4W$ 

Complementary part number ZXTN25020DZ



## **Description**

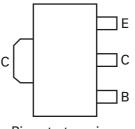
Packaged in the SOT89 outline this new low saturation 20V PNP transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions

#### **Features**

- · High peak current
- · Low saturation voltage
- · High gain
- SOT89 package

## **Applications**

- · DC-DC converters
- · Load switch
- Motor drive
- · Disconnect switch
- · MOSFET and IGBT gate drive



Pinout - top view

## **Ordering information**

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP25020DZTA	7	12	1000

## **Device marking**

• 1L5

## **Absolute maximum ratings**

Parameter	Symbol	Limit	Unit
Collector-Base voltage	V <sub>CBO</sub>	-25	V
Collector-Emitter voltage	V <sub>CEO</sub>	-20	V
Emitter-Base voltage (reverse blocking)	V <sub>ECO</sub>	-4	V
Emitter-Base voltage	V <sub>EBO</sub>	-7	V
Continuous Collector current <sup>(c)</sup>	I <sub>C</sub>	-5	Α
Base current	I <sub>B</sub>	-1	Α
Peak pulse current	I <sub>CM</sub>	-10	Α
Power dissipation at T <sub>A</sub> =25°C <sup>(a)</sup>	P <sub>D</sub>	1.1	W
Linear derating factor		8.8	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(b)</sup>	P <sub>D</sub>	1.8	W
Linear derating factor		14.4	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(c)</sup>	P <sub>D</sub>	2.4	W
Linear derating factor		19.2	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(d)</sup>	P <sub>D</sub>	4.46	W
Linear derating factor		35.7	mW/°C
Power dissipation at T <sub>C</sub> =25°C <sup>(e)</sup>	P <sub>D</sub>	15.7	W
Linear derating factor		126	mW/°C
Operating and storage temperature range	T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

## Thermal resistance

Parameter	Symbol	Limit	Unit	
Junction to ambient <sup>(a)</sup>	$R_{\Theta JA}$	117	°C/W	
Junction to ambient <sup>(b)</sup>	$R_{\Theta JA}$	68	°C/W	
Junction to ambient <sup>(c)</sup>	$R_{\Theta JA}$	51	°C/W	
Junction to ambient <sup>(d)</sup>	$R_{\Theta JA}$	28	°C/W	
Junction to case <sup>(e)</sup>	$R_{\Theta JC}$	7.95	°C/W	

#### NOTES:

<sup>(</sup>a) For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

 $<sup>\</sup>textbf{(b)}\,Mounted\,\,on\,\,25mm\,\,x\,\,25mm\,\,x\,\,0.6mm\,\,FR4\,\,PCB\,\,with\,\,high\,\,coverage\,\,of\,\,single\,\,sided\,\,1oz\,\,copper,\,\,in\,\,still\,\,air\,\,conditions.$ 

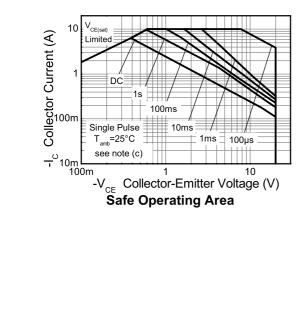
<sup>(</sup>c) Mounted on  $50 \text{mm} \times 50 \text{mm} \times 0.6 \text{mm}$  FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions.

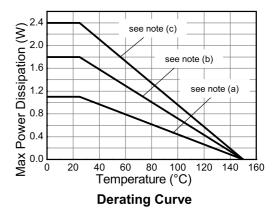
<sup>(</sup>d) As (c) above measured at t<5 seconds.

<sup>(</sup>e) Junction to case (collector tab). Typical.

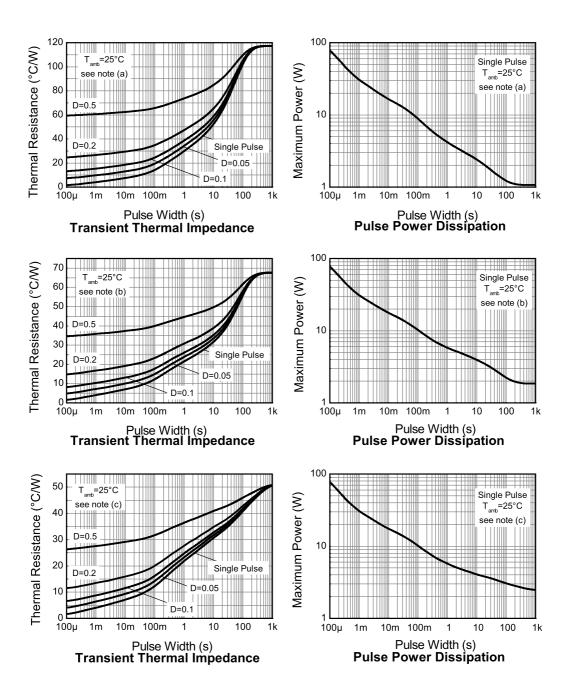
# **ZXTP25020DZ**

## Thermal characteristics





## Thermal characteristics



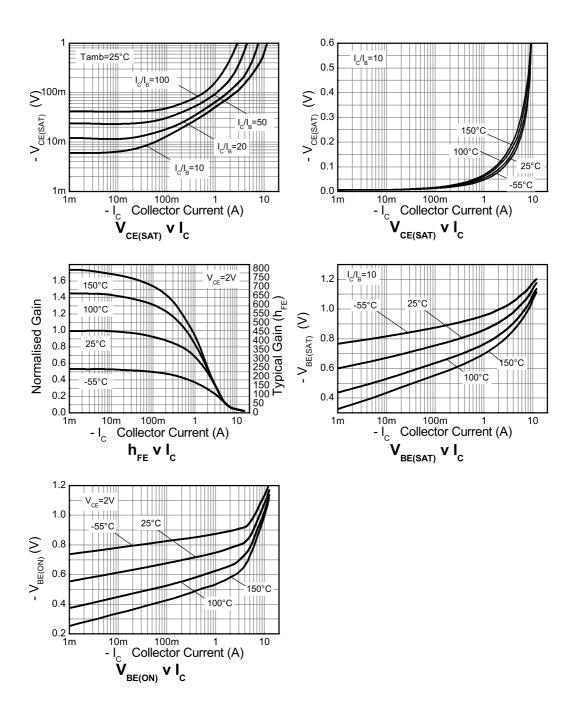
# Electrical characteristics (at T<sub>amb</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Collector-Base breakdown voltage	BV <sub>CBO</sub>	-25	-55		V	$I_C = -100 \mu A$
Collector-Emitter breakdown voltage	BV <sub>CEO</sub>	-20	-45		V	I <sub>C</sub> = -10mA (*)
Emitter-Collector breakdown voltage (reverse blocking)	BV <sub>ECX</sub>	-4	-8.5		V	$I_E = -100\mu A$ , $R_{BC} < 1k\Omega$ or $0.25V > V_{BC} > -0.25V$
Emitter-Collector breakdown voltage (reverse blocking)	BV <sub>ECO</sub>	-4	-8.5		V	$I_E = -100\mu A$
Emitter-Base breakdown voltage	BV <sub>EBO</sub>	-7	-8.3		V	I <sub>E</sub> = -5.6V
Collector-Base cut-off	I <sub>CBO</sub>		<1	-50	nA	V <sub>CB</sub> = -25V
current				-0.5	μΑ	$V_{CB} = -25V, T_{amb} = 100^{\circ}C$
Emitter cut-off current	I <sub>EBO</sub>		<1	-50	nA	V <sub>EB</sub> = -5.6V
Collector-Emitter	V <sub>CE(sat)</sub>		-50	-65	mV	$I_C = -1A$ , $I_B = -100 \text{mA}^{(*)}$
saturation voltage			-150	-215	mV	$I_C = -1A$ , $I_B = -10mA^{(*)}$
			-185	-245	mV	$I_C = -2A$ , $I_B = -40mA^{(*)}$
			-195	-265	mV	$I_C = -5A$ , $I_B = -500 \text{mA}^{(*)}$
Base-Emitter saturation voltage	V <sub>BE(sat)</sub>		-1010	-1100	mV	$I_C = -5A$ , $I_B = -500 \text{mA}^{(*)}$
Base-Emitter turn-on voltage	V <sub>BE(on)</sub>		-870	-1000	mV	$I_C = -5A$ , $V_{CE} = -2V^{(*)}$
Static forward current	h <sub>FE</sub>	300	450	900		$I_C = -10 \text{mA}, V_{CE} = -2V^{(*)}$
transfer ratio		200	310			$I_C = -1A$ , $V_{CE} = -2V^{(*)}$
		45	85			$I_C = -5A$ , $V_{CE} = -2V^{(*)}$
			20			$I_C = -10A$ , $V_{CE} = -2V^{(*)}$
Transition frequency	f <sub>T</sub>		290		MHz	$I_C = -50 \text{mA}, V_{CE} = -10 \text{V}$ f = 100MHz
Input capacitance	C <sub>ibo</sub>		157	400	pF	V <sub>EB</sub> = -0.5V, f = 1MHz <sup>(*)</sup>
Output capacitance	C <sub>obo</sub>		21	30	pF	$V_{CB} = -10V, f = 1MHz^{(*)}$
Delay time	t <sub>d</sub>		14.2		ns	
Rise time	t <sub>r</sub>		16.3		ns	$V_{CC} = -10V, I_{C} = -1A,$
Storage time	t <sub>s</sub>		186		ns	$I_{B1} = -I_{B2} = -50 \text{mA}$
Fall time	t <sub>f</sub>		32.7		ns	]

### NOTES:

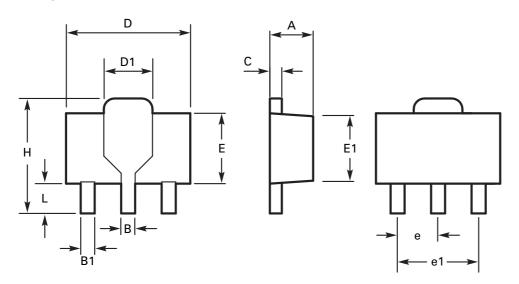
<sup>(\*)</sup> Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s; duty cycle  $\leq$  2%.

## **Typical characteristics**



# **ZXTP25020DZ**

# Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50	BSC	0.059	BSC
С	0.35	0.44	0.014	0.017	e1	3.00	BSC	0.118	BSC
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.52	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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